

ATTORNEY'S DOCKET NO.  
TI-33824  
(032350.B550)

PATENT APPLICATION

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TRANSMITTAL FOR U.S. PATENT APPLICATION  
UNDER 37 CFR §1.53(b)

Mail Stop Patent Application  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Transmitted herewith for filing is the original patent application of:

Inventor: Rabah Mezenner

For: IMPROVED VIA ADHESION IN MULTILAYER MEMS STRUCTURE

Enclosed are:

X  Specification, Claims and Abstract (  20  Pages);

X  Drawing(s)  4  Total Sheet(s) of  X  Formal   Informal);

Combined Declaration and Power of Attorney (1 Page)  
  Newly executed (original or copy);

An Assignment (   Page) of the invention to Texas Instruments Incorporated is attached. A separate cover sheet (   Page) in compliance with 37 C.F.R. § 3.28 and § 3.31 is included. Please charge the Assignment recordal fee of \$40.00 pursuant to 37 C.F.R. § 1.21(h) to Deposit Account No. 20-0668 of Texas Instruments Incorporated;

X  Certificate of Mailing (1 Page);

X  TI Return Receipt Postcard (1);

X  Baker Botts Return Receipt Postcard (1); and

X  This Transmittal (2 pages).

Information Disclosure Statement (   Page)  
with PTO 1449 (   Page) with references

Applicant is:



☒ Large Entity

☐ Small Entity

The accompanying application is:

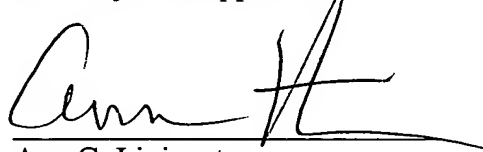
☒ Original.

☐ Continuation ☐ Divisional ☐ Continuation-In-Part (CIP) of prior application No. \_\_\_\_\_ which is hereby incorporated by reference therein.

FEE CALCULATION					FEE
	Number		Number Extra	Rate	Basic Fee \$770.00
Total Claims	16	20	0	X \$18.00 =	\$ .00
Independent Claims	4	3	1	X \$86.00 =	\$ 86.00
TOTAL FILING FEE =					\$ 856.00

☒ Please charge the filing fee of \$856.00 and any other fee required by this paper, or credit any overpayment, to Deposit Account No. 20-0668 of TEXAS INSTRUMENTS INCORPORATED. **This document is being transmitted in duplicate.**

BAKER BOTTS L.L.P.  
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Registration No 32,479

Date: 12/31/03

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☒ Customer Number

**23494**

ATTORNEY DOCKET  
TI-33824

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Rabah Mezenner

Date Filed: December 31, 2003

Title: IMPROVED VIA ADHESION IN MULTILAYER MEMS  
STRUCTURE

**Mail Stop Patent Application**

Commissioner for Patents

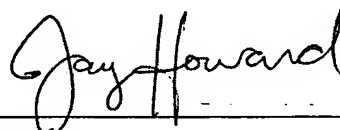
P.O. Box 1450

Alexandria, Virginia 22313-1450

Dear Sir:

CERTIFICATE OF MAILING BY EXPRESS MAIL

I hereby certify that the attached Filing Fee Transmittal (2 pages), the Patent Application (20 pages), Formal Drawings (4 pages), a Baker Botts L.L.P. return receipt postcard (1 card), a Texas Instruments Incorporated return receipt postcard (1 card), and this Certificate of Mailing are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 C.F.R. § 1.10 and are addressed to the Mail Stop Patent Application, Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450.



\_\_\_\_\_  
Jay Howard

Date: December 31, 2003

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